



Main Features

- 2nd Generation Intel® Core™ Mobile Processors
- Intel® QM67/HM65 PCH
- 1x DDR3 SO-DIMM socket support non-ECC DDR3 800/1066/1333MHz up to 8GB
- Type 2 COM Express Module Support 6 Express Lanes, 32 bit PCI Interface, One IDE and Gigabit LAN

Product Overview

The ICES 267 is a COM Express Type 2 basic module featuring Intel® QM67/HM65 Platform Control Hub, which supports 2nd generation Intel® Core™ Mobile processors and one DDR3 SO-DIMM memory socket up to 8GB. The ICES 267 integrated with Intel® HD graphics or expands via PCI Express Graphic 1x 16 lane to carrier board; it also supports other display types include LFP or Dual channel LVDS. The high performance ICES 267 COM Express Module supports 4x SATA, 8x USB2.0 and 6X PCIe x1 lanes through the carrier board. It is compatible with ICEB 8050 carrier board and in-house designed ICES 267 F-kits from NEXCOM.

Specifications

CPU Support

- Support 2nd generation Intel® Core™ processor family, rPGA 988

Processor	i5-2510E	i3-2330E	Celeron® B810
# of Core	2	2	2
Clock Speed	2.5GHz	2.2GHz	1.6GHz
Max. TDP	35W	35W	35W

Main Memory

- One DDR3 1066/1333 MHz SO-DIMM, up to 8GB

Platform Control Hub

- QM67/ HM65

BIOS

- AMI System BIOS
- Plug and play support

Display

- Intel® HD graphics solution
- One PCI Express X 16 Lane down to the carried board
- Drive a standard progressive scan analog monitor with resolution up to 2048 x 1536 @ 60Hz
- Supports LVDS 18/24-bit & single/dual channel interface

Audio

- HD audio interface

On-board LAN

- Intel® 82579LM Gigabit Ethernet, support iAMT 7.0 (supported with QM67 only)
- Support boot from LAN, wake on LAN function
- Signals down to I/O board

COM Express Connector

- AB
VGA/ LVDS/ 8x USB 2.0/ HD Audio/ 3x SATA/ LAN/ GPIO/ LPC bus
One PCIe X4/ two PCIe X1/ SMBus (I2C)/ SPI BIOS
- CD
PCIe x16/ IDE/ PCI

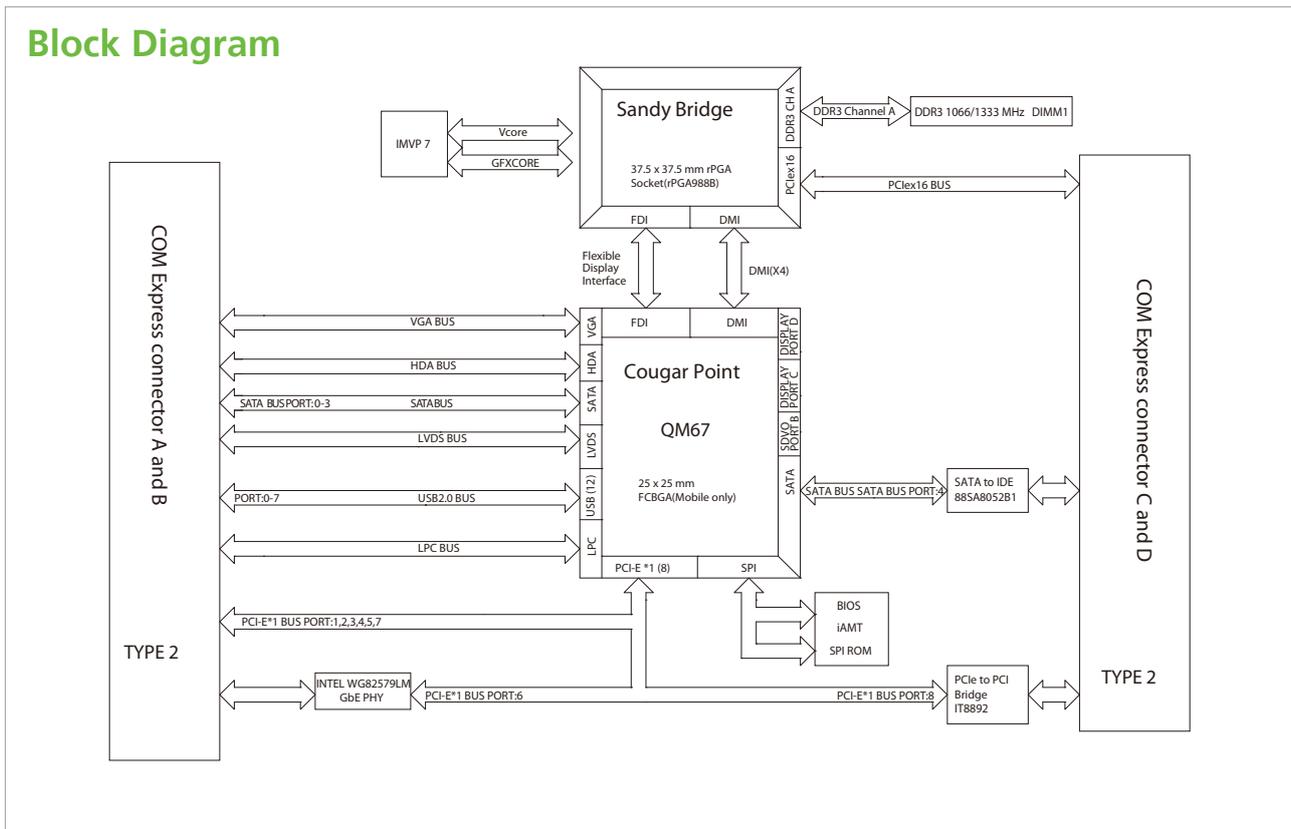
Power Requirements

- +12V, +5VSB, +3.3V RTC power

Dimensions

- 95mm (W) x 125mm (L)

Block Diagram



Environment

- Board Level Operating temperatures: -15°C to 60°C
- Storage temperatures: -20°C to 80°C
- Relative humidity:
 - 10% to 90% (operating, non-condensing)
 - 5% to 95% (non-operating, non-condensing)

Certifications

- CE approval
- FCC Class A

Ordering Information

◆ ICES 267 (P/N:10K00026700X0)

COM Express Type 2 basic module support Intel® Socket rPGA 988, 2nd generation Core™ mobile processor family, DDR3/ PCEe x16/ PCI/ IDE/ GbE/ LVDS/ audio interface

◆ ICEB 8050C (P/N: 10KB0805000X00)

COM Express Type 2 R2.0 evaluation board with PCIe/ PCI/ SATA/ CF/ mPCIe/ IDE/ COM/ USB/ VGA/ GbE and bootable from cFAST or Mini-SATA.

◆ ICES 267 F-Kit (P/N: 10K00026706X00)

Active Fan Kits with heat-spreader, heat-sink and Cooling fan in-house designed for ICES267